

1. Record Nr.	UNISA996386244003316
Autore	Bolton Robert <1572-1631.>
Titolo	Helpes to humiliation. By R.B [[electronic resource]]
Pubbl/distr/stampa	Oxford, : Printed by William Turner, for Michael Sparke [in London], dwelling in Greene Arbor, 1631
Descrizione fisica	[10], 164, [2] p
Altri autori (Persone)	I. S <fl. 1631-1638.>
Soggetti	Humility
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	R.B. = Robert Bolton. Editor's preface signed: I.S. Some print faded and show-through. Reproduction of the original in the Bodleian Library.
Sommario/riassunto	eebo-0014

2. Record Nr.	UNINA9910134756903321
Titolo	2015 20th IEEE European Test Symposium (ETS) : ETS 2015 : May 25th-29th 2015, Cluj-Napoca, Romania // Institute of Electrical and Electronics Engineers
Pubbl/distr/stampa	Piscataway, New Jersey : , : IEEE, , 2015
ISBN	1-4799-7603-2
Descrizione fisica	1 online resource (211 pages) : illustrations
Disciplina	620.0044
Soggetti	Automatic test equipment Electronic digital computers - Circuits - Testing Integrated circuits - Testing
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Sommario/riassunto	ETS15 is dedicated to presenting and discussing results, applications, emerging ideas and trends in the following topics Analog Test ATE Hardware and Software Board Test and Diagnosis Boundary Scan, BIST and Self Repair Current Based and Defect Based Test Delay and Performance Test Dependability and Functional Safety DfT Design for Manufacturing Diagnosis and Silicon Debug Economics of Test Emerging Technologies Failure Analysis Fault Modeling and Simulation Fault Tolerance GPU Test High Speed I O Test Low Power IC Test Memory Test and Repair MEMS Test Microprocessor Test Mixed Signal Test Multi Many core Processor Test Nanotechnology Test On line Test Power Issues in Test Reconfigurable System Test RF Test Security and Trust Issues in Test Sensor Test Signal Integrity Test SIP, Stacked, 3D IC Test SoC Test Soft Errors Standards in Test System Test Test compression Test Quality & Synthesis Thermal Issues in Test Validation and Verification Variability Issues in Test Yield Analysis.